

<b>ENGINEERING DEPT.</b>		<b>PRODUCT SPECIFICATION</b> <b>For CI22 IDC Series Connector System</b>	<b>SPEC.NO.: SPCI151B</b>
<b>REVISIONS</b>	<b>ECNT120150</b>		<b>PAGE: 1/4</b>

**1. SCOPE:**

This specification contains the test requirement of subject connectors when tested under the condition and procedure with terminals crimped on the specified maximum size wire

**2. APPLICABLE STANDARDS:**

MIL - STD - 202	Methods for test of connectors for electronic equipment
EIA - 364	Test methods for electrical connectors

**3. APPLICABLE SERIES NO.: CI22 IDC Type Series**

**4. SHAPE, CONSTRUCTION AND DIMENSIONS**

See attached drawings

**5. MATERIALS**

See attached drawings

**6. ACCOMMODATED P.C.BOARD**

6.1 Thickness: 0.8 mm (.031") ~ 1.6 mm (.063")

6.2 P.C. Board Layout: See attached drawings

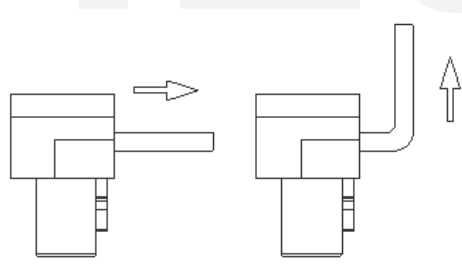
**REVIEWED :** Eisley **APPROVED :** Sun **VERIFIED :** Michelle .

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**7. ELECTRICAL PERFORMANCE:**

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		3A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. , 100 mA max.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 1000 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 1000 MΩ

**8. MECHANICAL PERFORMANCE:**

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Wire size	Specified wire size	Accepts AWG#24,#28
8.2	Pin retention force	Push pin from insulator base at speed 25± 3 mm per minute	More than 1.5 Kgf
8.3	Wire pull out force	Measure force to insertion using 0.50 mm square pin at speed 25± 3 mm per minute   <u>Parallel direction</u> <u>Perpendicular direction</u>	<u>Parallel direction:</u> More than 1.50 Kgf <u>Perpendicular direction:</u> More than 1.50 Kgf
8.4	Single contact insertion force	Measure force to insertion using 0.64 mm square pin at speed 25± 3 mm per minute	0.7 Kgf max.
8.5	Single contact withdrawal force	Measure force to withdrawal using 0.64 mm square pin at speed 25± 3 mm per minute	0.1 Kgf min.
8.6	Mating & Un-mating force	Insert and withdraw connector at speed of 25 ± 3 mm per minute	See Item 11
8.7	Durability	Connector shall be subjected to 100 cycles of insertion and withdrawal	Contact resistance: Less than twice of initial

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9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Then carried the rated current	30° C max.
9.2	Vibration	1.5 mm 10-55-10 HZ / minute each 2 hours for X , Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.3	Solder ability	<b>Tin-Lead Process:</b> Soldering time: 5 ± 0.5 second Soldering pot: 230 ± 5° C <b>Lead-Free Process:</b> Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5° C	Minimum: 90% of immersed area
9.4	Resistance to soldering heat	<b>Tin-Lead Process:</b> Soldering time: 5 ± 0.5 second Soldering pot: 240 ± 5° C <b>Lead-Free Process</b> Soldering time: 5 ± 0.5 second Soldering pot: 260 ± 5° C	No damage
9.5	Heat aging	105 ± 2° C , 96 hours	No damage
9.6	Humidity	40 ± 2° C , 90-95% RH , 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3
9.7	Temperature cycling	Five cycle consists of : (1)-55 <sup>+0</sup> / <sub>-3</sub> ° C , 30 min. (2)Room temp. 10-15 min. (3) 85 <sup>+3</sup> / <sub>-0</sub> ° C , 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial

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	ITEM	TEST CONDITION	REQUIREMENT
9.8	Salt spray	Temperature: $35 \pm 3^{\circ}\text{C}$ Solution: $5 \pm 1\%$ Spray time: $48 \pm 4$ hours (Stamping before plated) Spray time: $24 \pm 4$ hours (Stamping after plated) Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed. The specimens shall be suspended from the top using waxed twine, string or nylon thread. The test only define the plating area, without plating area (as copper cross section) will not be defined. (EIA 364-26B / MIL-STD-202 Method 101)	Appearance: No damage Contact resistance: Less than twice of initial

10. AMBIENT TEMPERATURE RANGE:  $-25$  to  $+105^{\circ}\text{C}$

11. Mating and Un-mating Force:

Unit: Kgf

NO. OF CIRCUITS	INSERTION FORCE (Max.)	WITHDRAWAL FORCE (Min.)
2	2.5	0.4
3	3.0	0.5
4	3.5	0.9
5	3.5	0.9
6	4.0	1.2
7	4.5	1.5
8	4.5	1.5
9	5.0	1.8
10	5.0	1.8
11	5.5	2.1
12	5.5	2.1
13	6.0	2.4
14	6.0	2.4
15	6.5	2.7